L Number	Hits	Search Text	DB	Time stamp
-	350680	438/\$.ccls. or 257/\$.ccls.	USPAT;	2004/08/06
		,,	US-PGPUB;	22:30
			EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
-	2730		USPAT;	2004/08/06
		same (reform\$3 or reflow\$3 or melt\$3 or	US-PGPUB;	23:42
		coagulat\$3)) same ((contact adj hole) or	EPO; JPO;	
		via or trench)	DERWENT;	
	1255	(/420/0 == 1 = == 257/0 == 1 =) === 1 /== 1	IBM_TDB	2004/08/06
-	1355	((438/\$.ccls. or 257/\$.ccls.) and (metal	USPAT; US-PGPUB;	23:33
		same (reform\$3 or reflow\$3 or melt\$3 or coagulat\$3)) same ((contact adj hole) or	EPO; JPO;	23:33
	_	via or trench)) and (heat\$3 same metal)	DERWENT;	
		Via of clenchy, and (heacy) same metaly	IBM TDB	
_	321	(((438/\$.ccls. or 257/\$.ccls.) and (metal	USPAT;	2004/08/06
l	521	same (reform\$3 or reflow\$3 or melt\$3 or	US-PGPUB;	23:33
		coagulat\$3)) same ((contact adj hole) or	EPO; JPO;	
		via or trench)) and (heat\$3 same metal))	DERWENT;	
ļ		and (circuit same board)	IBM_TDB	
-	153	((((438/\$.ccls. or 257/\$.ccls.) and	USPAT;	2004/08/06
		(metal same (reform\$3 or reflow\$3 or	US-PGPUB;	22:44
		melt\$3 or coagulat\$3)) same ((contact adj	EPO; JPO;	
		hole) or via or trench)) and (heat\$3 same	DERWENT;	
		metal)) and (circuit same board)) and	IBM_TDB	
		(first near10 metal) and (second near10		
	1	metal)	HCDAM.	2004/09/06
-	1	(((((438/\$.ccls. or 257/\$.ccls.) and	USPAT; US-PGPUB;	2004/08/06
		<pre>(metal same (reform\$3 or reflow\$3 or melt\$3 or coagulat\$3)) same ((contact adj</pre>	EPO; JPO;	22:35
		hole) or via or trench)) and (heat\$3 same	DERWENT;	
		metal)) and (circuit same board)) and	IBM TDB	
		(first near10 metal) and (second near10		
		metal)) and coagulat\$3		
-	24	((((438/\$.ccls. or 257/\$.ccls.) and	USPAT;	2004/08/06
		(metal same (reform\$3 or reflow\$3 or	US-PGPUB;	23:33
		melt\$3 or coagulat\$3)) same ((contact adj	EPO; JPO;	
		hole) or via or trench)) and (heat\$3 same	DERWENT;	
		metal)) and (circuit same board)) and	IBM_TDB	
		((first near10 metal) and (second near10		
		metal) same fill\$3 same ((contact adj		
_	6798	hole) or via or trench)) ((438/597) or (438/598) or (438/614) or	USPAT;	2004/08/06
_	0/96	(438/615) or (438/618) or (438/652) or	USPAT; US-PGPUB;	23:32
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	23.32
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.	IBM TDB	
-	272	(((438/597) or (438/598) or (438/614) or	USPAT;	2004/08/06
		(438/615) or (438/618) or (438/652) or	US-PGPUB;	23:33
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (metal same	IBM_TDB	
		(reform\$3 or reflow\$3 or melt\$3 or		
		coagulat\$3)) same ((contact adj hole) or		
_	150	via or trench)	HCDATT -	2004/09/06
_	150	((((438/597) or (438/598) or (438/614) or (438/615) or (438/618) or (438/652) or	USPAT; US-PGPUB;	2004/08/06
İ		(438/658) or (438/660) or (438/666) or	EPO; JPO;	23.33
		(438/667) or (438/669) or	DERWENT;	
		via or trench)) and (heat\$3 same metal)		
		(438/672)).CCLS.) and (metal same (reform\$3 or reflow\$3 or melt\$3 or coagulat\$3)) same ((contact adj hole) or	IBM_TDB	

-	27	(((((438/597) or (438/598) or (438/614)	USPAT;	2004/08/06
		or (438/615) or (438/618) or (438/652) or	US-PGPUB;	23:33
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (metal same	IBM_TDB	
	i	(reform\$3 or reflow\$3 or melt\$3 or		
	1	coagulat\$3)) same ((contact adj hole) or		
		<pre>via or trench)) and (heat\$3 same metal))</pre>		
		and (circuit same board)		
-	3	((((((438/597) or (438/598) or (438/614)	USPAT;	2004/08/06
		or (438/615) or (438/618) or (438/652) or	US-PGPUB;	23:41
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	
	.000	(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (metal same	IBM TDB	
		(reform\$3 or reflow\$3 or melt\$3 or	_	
!	1	coagulat\$3)) same ((contact adj hole) or		
1'	1	via or trench)) and (heat\$3 same metal))		
		and (circuit same board)) and ((first		
		near10 metal) and (second near10 metal)		
		same fill\$3 same ((contact adj hole) or		
		via or trench))		
-	281	(((438/597) or (438/598) or (438/614) or	USPAT;	2004/08/06
		(438/615) or (438/618) or (438/652) or	US-PGPUB;	23:41
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	
		(438/667) or (438/669) or	DERWENT;	
i		(438/672)).CCLS.) and (Bi or bismuth)	IBM TDB	
_	203	((((438/597) or (438/598) or (438/614) or	USPAT;	2004/08/06
	200	(438/615) or (438/618) or (438/652) or	US-PGPUB;	23:42
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	23.42
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (Bi or bismuth))	IBM TDB	
		and (cu or copper)	1011_100	
_	30	(((((438/597) or (438/598) or (438/614)	USPAT;	2004/08/06
		or (438/615) or (438/618) or (438/652) or	US-PGPUB;	23:42
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	23.42
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (Bi or bismuth))	IBM TDB	
		and (cu or copper)) and (metal same	1511_155	
		(reform\$3 or reflow\$3 or melt\$3 or		
		coagulat\$3)) same ((contact adj hole) or		
		via or trench)		İ
_	18	((((((438/597) or (438/598) or (438/614)	USPAT;	2004/08/06
		or (438/615) or (438/618) or (438/652) or	US-PGPUB;	23:42
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (Bi or bismuth))	IBM_TDB	
		and (cu or copper)) and (metal same	1011_100	İ
		(reform\$3 or reflow\$3 or melt\$3 or		
		coagulat\$3)) same ((contact adj hole) or		
		via or trench)) and (plating or plated)		
1 -	12		USPAT;	2004/08/06
		or (438/615) or (438/618) or (438/652) or	US-PGPUB;	23:43
		(438/658) or (438/660) or (438/666) or	EPO; JPO;	
		(438/667) or (438/669) or	DERWENT;	
		(438/672)).CCLS.) and (Bi or bismuth))	IBM TDB	
		and (cu or copper)) and (metal same	1011_100	
		(reform\$3 or reflow\$3 or melt\$3 or		
		coagulat\$3)) same ((contact adj hole) or		
		via or trench)) and (plating or plated))		
		and (Sn or Ag or indium or Zn or Sb)		
L		The fair of the of the of the of the	[l